

ABSTRACT OF THE DISCLOSURE

A semiconductor device comprises: a semiconductor chip; an extension portion which contacts the side surfaces of the semiconductor chip to thereby surround the semiconductor chip; 5 an insulating film which is formed such that a part of each of the plurality of electrode pads is exposed; a plurality of wiring patterns individually electrically connected to each of the electrode pads, respectively and extended from the electrode pads to the upper side of the extension portion; and a plurality 10 of external terminals provided over the wiring patterns in a region including the upper side of the extension portion.